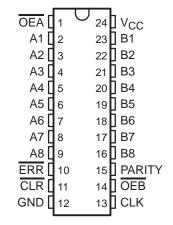
- State-of-the-Art *EPIC-IIB™* BiCMOS Design **Significantly Reduces Power Dissipation**
- ESD Protection Exceeds 2000 V Per MIL-STD-883, Method 3015; Exceeds 200 V Using Machine Model (C = 200 pF, R = 0)
- Latch-Up Performance Exceeds 500 mA Per **JEDEC Standard JESD-17**
- Typical V_{OLP} (Output Ground Bounce) < 1 V at $V_{CC} = 5 \text{ V}$, $T_A = 25^{\circ}\text{C}$
- High-Drive Outputs (-32-mA IOH, 64-mA IOI)
- **Parity Error Flag With Parity** Generator/Checker
- Register for Storage of the Parity Error Flag
- **Package Options Include Plastic** Small-Outline (DW) Packages, Ceramic Chip Carriers (FK), and Plastic (NT) and Ceramic (JT) DIPs

description

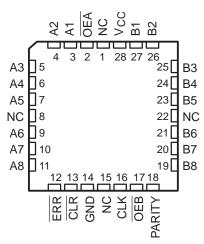
The 'ABT833 8-bit to 9-bit parity transceivers are designed for communication between data buses. When data is transmitted from the A bus to the B bus, a parity bit is generated. When data is transmitted from the B bus to the A bus with its corresponding parity bit, the open-collector parity-error (ERR) output indicates whether or not an error in the B data has occurred. The output-enable (OEA and OEB) inputs can be used to disable the device so that the buses are effectively isolated. The 'ABT833 provide true data at their outputs.

A 9-bit parity generator/checker generates a parity-odd (PARITY) output and monitors the parity of the I/O ports with the \overline{ERR} flag. \overline{ERR} is clocked into the register on the rising edge of the clock (CLK) input. The error flag register is cleared with a low pulse on the clear (CLR) input. When both OEA and OEB are low, data is transferred from the A bus to the B bus and inverted parity is generated. Inverted parity is a forced error condition that gives the designer more system diagnostic capability.

SN54ABT833 . . . JT PACKAGE SN74ABT833... DW OR NT PACKAGE (TOP VIEW)



SN54ABT833...FK PACKAGE (TOP VIEW)



NC - No internal connection



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

EPIC-IIB is a trademark of Texas Instruments Incorporated



description (continued)

To ensure the high-impedance state during power up or power down, $\overline{\text{OE}}$ should be tied to V_{CC} through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

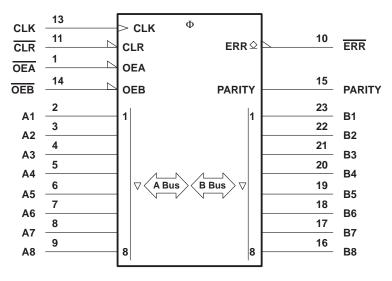
The SN54ABT833 is characterized for operation over the full military temperature range of -55°C to 125°C. The SN74ABT833 is characterized for operation from -40°C to 85°C.

FUNCTION TABLE

			INPUTS	3			OUTP	UT AND I/O		
OEB	OEA	CLR	CLK	$\begin{array}{c} \text{Ai} \\ \Sigma \text{ OF H's} \end{array}$	Bi† Σ OF H's	Α	В	PARITY	ERR‡	FUNCTION
L	Н	Х	Х	Odd Even	NA	NA	Α	L H	NA	A data to B bus and generate parity
Н	L	Н	1	NA	Odd Even	В	NA	NA	H L	B data to A bus and check parity
Х	Х	L	Х	Х	Х	Х	NA	NA	Н	Check error-flag register
н	н	H L H	No↑ No↑ ↑	X X Odd Even	Х	Z	Z	Z	NC H H L	Isolation§
L	L	Х	Х	Odd Even	NA	NA	Α	H L	NA	A data to B bus and generate inverted parity

NA = not applicable, NC = no change, X = don't care

logic symbol¶



[¶] This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12. Pin numbers shown are for the DW, JT, and NT packages.

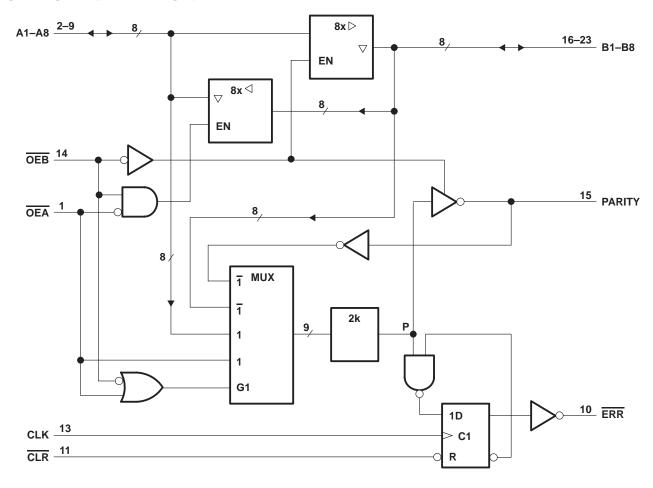


[†]Summation of high-level inputs includes PARITY along with Bi inputs.

[‡] Output states shown assume ERR was previously high.

[§] In this mode, ERR (when clocked) shows inverted parity of the A bus.

logic diagram (positive logic)



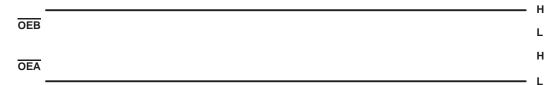
Pin numbers shown are for the DW, JT, and NT packages.

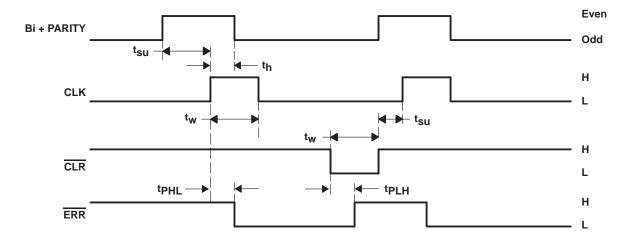
ERROR-FLAG FUNCTION TABLE

INPUTS		INTERNAL TO DEVICE	OUTPUT PRE-STATE	OUTPUT ERR	FUNCTION
CLR	CLK	POINT P	ERR _{n-1} †	EKK	
Н	1	Н	Н	Н	
Н	\uparrow	X	L	L	Sample
Н	\uparrow	L	X	L	
L	Х	Х	Х	Н	Clear

†The state of ERR before any changes at CLR, CLK, or point P

error-flag waveforms





absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V _{CC}	\dots -0.5 V to 7 V
Input voltage range, V _I (except I/O ports) (see Note 1)	\dots -0.5 V to 7 V
Voltage range applied to any output in the high or power-off state, V _O	–0.5 V to 5.5 V
Current into any output in the low state, IO: SN54ABT833	96 mA
SN74ABT833	128 mA
Input clamp current, I _{IK} (V _I < 0)	–18 mA
Output clamp current, I _{OK} (V _O < 0)	–50 mA
Package thermal impedance, θ _{JA} (see Note 2): DW package	81°C/W
NT package	67°C/W
Storage temperature range, T _{stq}	. -65°C to 150°C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.
 - 2. The package thermal impedance is calculated in accordance with EIA/JEDEC Std JESD51, except for through-hole packages, which use a trace length of zero.



recommended operating conditions (see Note 3)

		SN54AE	3T833	SN74A	3T833	UNIT	
			MIN	MAX	MIN	MAX	UNIT
VCC	Supply voltage		4.5	5.5	4.5	5.5	V
VIH	High-level input voltage		2	h	2		V
VIL	Low-level input voltage			0.8		0.8	V
VI	Input voltage		0	Vcc	0	VCC	V
Vон	High-level output voltage	ERR	74	5.5		5.5	V
IOH	High-level output current	Except ERR	27/	-24		-32	mA
loL	Low-level output current		⁷ 0į	48		64	mA
Δt/Δν	Input transition rise or fall rate	Outputs enabled	Q	5		5	ns/V
TA	Operating free-air temperature		- 55	125	-40	85	°C

NOTE 3: Unused pins (input or I/O) must be held high or low to prevent them from floating.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CON	T	A = 25°(;	SN54A	BT833	SN74A	BT833	UNIT	
PAI	RAWEIER	TEST CON	IDITIONS	MIN	TYP†	MAX	MIN	MAX	MIN	MAX	UNII
VIK		V _{CC} = 4.5 V,	$I_{I} = -18 \text{ mA}$			-1.2		-1.2		-1.2	V
		$V_{CC} = 4.5 \text{ V},$	$I_{OH} = -3 \text{ mA}$	2.5			2.5		2.5		
\ \ _{\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\}	All outputs	$V_{CC} = 5 V$,	$I_{OH} = -3 \text{ mA}$	3			3		3		V
VOH	except ERR	V _{CC} = 4.5 V	$I_{OH} = -24 \text{ mA}$	2			2				V
		VCC = 4.5 V	$I_{OH} = -32 \text{ mA}$	2*					2		
Vai		V _{CC} = 4.5 V	I _{OL} = 24 mA			0.55		0.55			V
VOL		VCC = 4.5 V	I _{OL} = 64 mA			0.55*				0.55	٧
V _{hys}					100						mV
ЮН	ERR	V _{CC} = 4.5 V,	V _{OH} = 5.5 V			20		20		20	μΑ
ļ.,	Control inputs	V _{CC} = 5.5 V,	V _I = V _{CC} or GND			±1		#		±1	μA
l II	A or B ports	vCC = 5.5 v,	AL = ACC OLGIAD			±100		±100		±100	μΑ
Ι _Ι L	A or B ports	$V_{CC} = 0$,	V _I = GND			-50		– 50		-50	μΑ
loz _H ‡		V _{CC} = 5.5 V,	V _O = 2.7 V			50	<i></i>	50		50	μΑ
l _{OZL} ‡		V _{CC} = 5.5 V,	V _O = 0.5 V			-50	22	-50		-50	μΑ
l _{off}		$V_{CC} = 0$,	V_I or $V_O \le 4.5 \text{ V}$			±100	70,			±100	μΑ
ICEX		V _{CC} = 5.5 V, V _O = 5.5 V	Outputs high			50	Q	50		50	μА
IO§		V _{CC} = 5.5 V,	V _O = 2.5 V	-50	-100	-200¶	-50	-200¶	-50	-200¶	mA
		V _{CC} = 5.5 V,	Outputs high		1	250		250		250	μΑ
Icc	A or B ports	$I_{O} = 0$,	Outputs low		24	38¶		38¶		38¶	mA
		$V_I = V_{CC}$ or GND	Outputs disabled		0.5	250		250		250	μΑ
	Data innuta	V _{CC} = 5.5 V, One input at 3.4 V,	Outputs enabled			1.5		1.5		1.5	mA
∆lcc#	Data inputs	Other inputs at V _{CC} or GND	Outputs disabled			50		50		50	μΑ
	Control inputs	V _{CC} = 5.5 V, One inpu Other inputs at V _{CC} or				1.5		1.5		1.5	mA
Ci	Control inputs	V _I = 2.5 V or 0.5 V			4.5						pF
C _{io}	A or B ports	V _O = 2.5 V or 0.5 V			10.5						pF

^{*} On products compliant to MIL-PRF-38535, this parameter does not apply.

[†] All typical values are at $V_{CC} = 5 \text{ V}$.

[‡] The parameters I_{OZH} and I_{OZL} include the input leakage current.

[§] Not more than one output should be tested at a time, and the duration of the test should not exceed one second.

[¶] These limits may vary among suppliers.

[#]This is the increase in supply current for each input that is at the specified TTL voltage level rather than VCC or GND.

timing requirements over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Figure 1)

		$V_{CC} = 5 \text{ V},$ $T_A = 25^{\circ}\text{C}$		SN54ABT833		SN74A	UNIT			
			MIN	MAX	MIN	MAX	MIN	MAX		
	Pulse duration	CLK high or low	3		3	1/2	3		ns	
t _W	ruise duration	CLR low	3		3 44		3		115	
		B or PARITY high	9.8		9.8	ζ	9.8			
t _{su}	Setup time before CLK↑	B or PARITY low	8.1		8.1		8.1		ns	
		CLR	2		0 2		2			
th	Hold time after CLK↑	B or PARITY	0		0		0		ns	

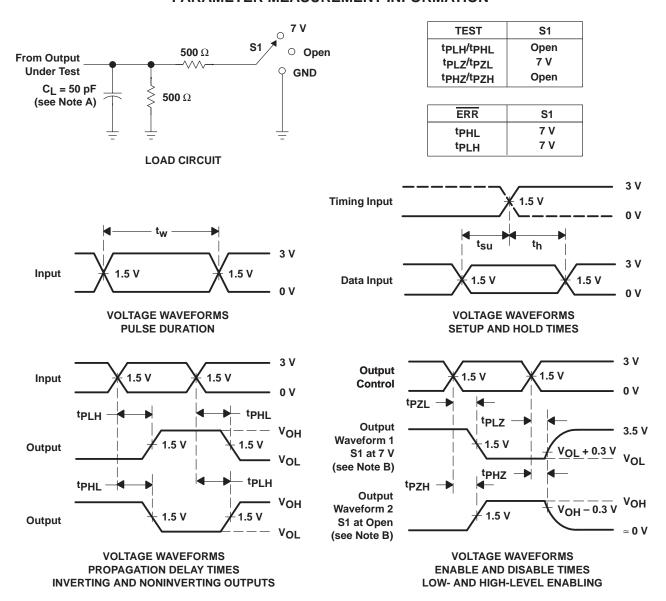
switching characteristics over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V T	CC = 5 V A = 25°C	<u>',</u>	SN54A	BT833	SN74AI	BT833	UNIT	
	(INFOT)	(0011-01)	MIN	TYP†	MAX	MIN	MAX	MIN	MAX		
^t PLH	A or B	P.or A	1.2	2.8	4.8	1.2	5.4	1.2	5.3	no	
t _{PHL}	AUIB	B or A	1	3	4.8‡	1	5.4	1	5.3‡	ns	
^t PLH	А	PARITY	2.1	5.5	9.5	2.1	11.3	2.1	11.2	ns	
^t PHL	A	FANITI	2.5	5.3	9.7	2.5	11,1	2.5	11	119	
^t PZH	ŌĒ	PARITY	2.6	6.2	8.5	2.6	10.6	2.6	10.5	ns	
t _{PZL}		FARITI	2.6‡	5.8	8.6	2.6‡ <	10.1	2.6‡	10	110	
^t PLH	CLR	ERR	1	3.2	4.8‡	(-)	5.3	1	5.2	no	
^t PHL	CLK	EKK	1.2‡	2.8	5.7	1.2‡	6.3	1.2‡	6.2	ns	
^t PZH		A, B, or PARITY	1	3.7	5.8‡	Q 1	6.6	1	6.5‡		
^t PZL	ŌĒ	A, B, OI PARII I	1.3‡	3.8	5.8	1.3‡	6.6	1.3‡	6.5‡	ns	
^t PHZ	ŌĒ	A, B, or PARITY	1.9‡	4.4	7.3	1.9‡	8	1.9‡	7.9	no	
^t PLZ	OE .	A, B, OI PARTIT	2.2‡	4.4	7.7	2.2‡	8.2	2.2‡	8.1	ns	

 $[\]overline{\dagger}$ All typical values are at $V_{CC} = 5 \text{ V}$.

[‡]These limits may vary among suppliers.

PARAMETER MEASUREMENT INFORMATION



NOTES: A. C_L includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR \leq 10 MHz, $Z_Q = 50 \Omega$, $t_r \leq$ 2.5 ns, $t_f \leq$ 2.5 ns
- D. The outputs are measured one at a time with one transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms





PACKAGE OPTION ADDENDUM

6-Feb-2020

PACKAGING INFORMATION

Orderable Device	Status	Package Type	_	Pins	•	Eco Plan	Lead/Ball Finish	MSL Peak Temp	Op Temp (°C)	Device Marking	Samples
	(1)		Drawing		Qty	(2)	(6)	(3)		(4/5)	
SN74ABT833DW	ACTIVE	SOIC	DW	24	25	Green (RoHS & no Sb/Br)	NIPDAU	Level-1-260C-UNLIM	-40 to 85	ABT833	Samples

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) RoHS: TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

Green: TI defines "Green" to mean the content of Chlorine (CI) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

- (3) MSL, Peak Temp. The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.
- (4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.
- (5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.
- (6) Lead/Ball Finish Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.

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DW (R-PDSO-G24)

PLASTIC SMALL OUTLINE



NOTES: A. All linear dimensions are in inches (millimeters). Dimensioning and tolerancing per ASME Y14.5M-1994.

- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
- D. Falls within JEDEC MS-013 variation AD.



DW (R-PDSO-G24)

PLASTIC SMALL OUTLINE



NOTES:

- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Refer to IPC7351 for alternate board design.
- D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525
- E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.



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